



Material Content Data Sheet



Sales Product Name		TLE4963-2M		Issued		9. January 2019		
MA#		MA004275494						
Package		PG-SOT23-3-15		Weight*		9.82 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.302	3.08	3.08	30799	30799
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		73	
	non noble metal	titanium	7440-32-6	0.004	0.04		367	
	non noble metal	chromium	7440-47-3	0.011	0.11		1101	
wire	non noble metal	copper	7440-50-8	3.590	36.55	36.71	365540	367081
	noble metal	gold	7440-57-5	0.023	0.23	0.23	2303	2303
	encapsulation	organic material	carbon black	1333-86-4	0.054	0.55		5493
encapsulation	plastics	epoxy resin	-	1.160	11.81		118097	
	inorganic material	silicondioxide	60676-86-0	4.180	42.58	54.94	425700	549290
leadfinish	non noble metal	tin	7440-31-5	0.150	1.52	1.52	15238	15238
plating	noble metal	silver	7440-22-4	0.149	1.51	1.51	15130	15130
glue	plastics	epoxy resin	-	0.035	0.35		3528	
	noble metal	silver	7440-22-4	0.163	1.66	2.01	16631	20159
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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